

# Technical Data :

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R 2 0 0 C H 2 0 F J O

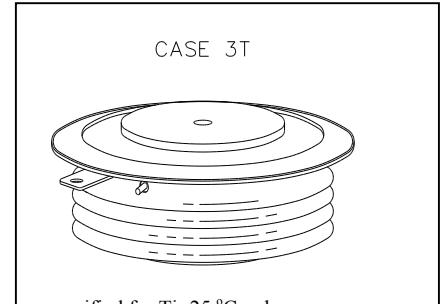
- Power Thyristor  
2000 V<sub>DRM</sub>;

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## HIGH POWER THYRISTOR FOR INVERTER AND CHOPPER APPLICATIONS

### Features:

- . All Diffused Structure
- . Interdigitated Amplifying Gate Configuration
- . Blocking capability up to 2000 volts
- . Guaranteed Maximum Turn-Off Time
- . High dV/dt Capability
- . Pressure Assembled Device



## ELECTRICAL CHARACTERISTICS AND RATINGS

### Blocking - Off State

Device Type	V <sub>RRM</sub> (1)	V <sub>DRM</sub> (1)	V <sub>RSM</sub> (1)
R200CH20FJO	2000	2000	2100

V<sub>RRM</sub> = Repetitive peak reverse voltage

V<sub>DRM</sub> = Repetitive peak off state voltage

V<sub>RSM</sub> = Non repetitive peak reverse voltage (2)

Repetitive peak reverse leakage and off state leakage	I <sub>RRM</sub> / I <sub>IDRM</sub>	15 mA 50 mA (3)
Critical rate of voltage rise (4)	dV/dt	500 V/μsec

### Conducting - on state

#### Notes:

All ratings are specified for T<sub>j</sub>=25 °C unless otherwise stated.

- (1) All voltage ratings are specified for an applied 50Hz/60Hz sinusoidal waveform over the temperature range -40 to +125 °C.
- (2) 10 msec. max. pulse width
- (3) Maximum value for T<sub>j</sub> = 125 °C.
- (4) Minimum value for linear and exponential waveshape to 80% rated V<sub>DRM</sub>. Gate open. T<sub>j</sub> = 125 °C.
- (5) Non-repetitive value.
- (6) The value of di/dt is established in accordance with EIA/NIMA Standard RS-397, Section 5-2-2-6. The value defined would be in addition to that obtained from a snubber circuit, comprising a 0.2 μF capacitor and 20 ohms resistance in parallel with the thristor under test.

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
RMS value of on-state current	I <sub>TRMS</sub>		900		A	Nominal value
Peak one cPSTCle surge (non repetitive) current	I <sub>TSM</sub>		7800 7200		A A	8.3 msec (60Hz), sinusoidal wave- shape, 180° conduction, T <sub>j</sub> = 125 °C 10.0 msec (50Hz), sinusoidal wave- shape, 180° conduction, T <sub>j</sub> = 125 °C
I square t	I <sup>2</sup> t		250000		A <sup>2</sup> s	8.3 msec and 10.0 msec
Latching current	I <sub>L</sub>		1000		mA	V <sub>D</sub> = 24 V; R <sub>L</sub> = 12 ohms
Holding current	I <sub>H</sub>		500		mA	V <sub>D</sub> = 24 V; I = 2.5 A
Peak on-state voltage	V <sub>TM</sub>		2.5		V	I <sub>TM</sub> = 1400 A; T <sub>j</sub> = 125 °C
Critical rate of rise of on-state current (5, 6)	di/dt		300		A/μs	Switching from V <sub>DRM</sub> ≤ 1000 V, non-repetitive
Critical rate of rise of on-state current (6)	di/dt		100		A/μs	Switching from V <sub>DRM</sub> ≤ 1000 V

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### Gating

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Peak gate power dissipation	P <sub>GM</sub>		200		W	t <sub>p</sub> = 40 us
Average gate power dissipation	P <sub>G(AV)</sub>		5		W	
Peak gate current	I <sub>GM</sub>		10		A	
Gate current required to trigger all units	I <sub>GT</sub>		400 200 150		mA	V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = -40 °C V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = +25 °C V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = +125 °C
Gate voltage required to trigger all units	V <sub>GT</sub>	0.25	5 3		V	V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = -40 °C V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = 0-125 °C V <sub>D</sub> = Rated V <sub>DRM</sub> ; R <sub>L</sub> = 1000 ohms; T <sub>j</sub> = + 125 °C
Peak negative voltage	V <sub>GRM</sub>		5		V	

### Dynamic

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Delay time	t <sub>d</sub>		3.0	1.5	μs	I <sub>TM</sub> = 500 A; V <sub>D</sub> = 1000 V Gate pulse: V <sub>G</sub> = 20 V; R <sub>G</sub> = 20 ohms; t <sub>r</sub> = 0.1 μs; t <sub>p</sub> = 20 μs
Turn-off time (with V <sub>R</sub> = -50 V)	t <sub>q</sub>		25		μs	I <sub>TM</sub> = 500 A; di/dt = 30 A/μs; V <sub>R</sub> ≥ -50 V; Re-applied dV/dt = 100 V/μs linear to 80% V <sub>DRM</sub> ; V <sub>G</sub> = 0; T <sub>j</sub> = 125 °C; Duty cPSTClе ≥ 0.01%
Reverse recovery charge	I <sub>rr</sub>		185		A	I <sub>TM</sub> = 500 A; di/dt = 30 A/μs; V <sub>R</sub> ≥ -50 V; T <sub>j</sub> = 125 °C

## THERMAL AND MECHANICAL CHARACTERISTICS AND RATINGS

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Operating temperature	T <sub>j</sub>	-40	+125		°C	
Storage temperature	T <sub>stg</sub>	-40	+150		°C	
Thermal resistance - junction to case	R <sub>θ(j-c)</sub>		0.040 0.080		°C/W	Double sided cooled Single sided cooled
Thermal resistamce - case to sink	R <sub>θ(c-s)</sub>		0.015 0.030		°C/W	Double sided cooled * Single sided cooled *
Mounting force	P	3000 13.3	3500 15.5		lb. kN	
Weight	W			9 225	oz. g	

\* Mounting surfaces smooth, flat and greased

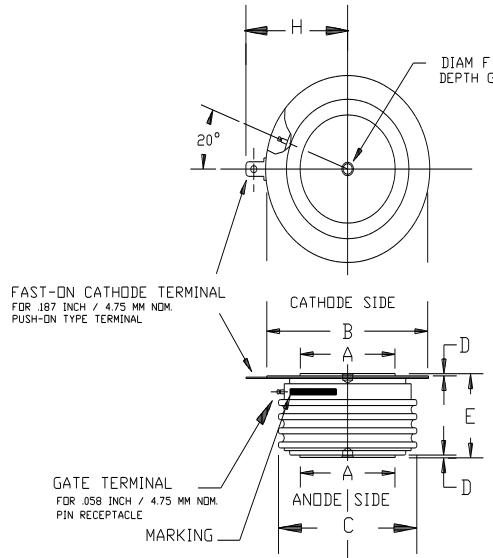
Note : for case outline and dimensions, see case outline drawing in page 3 of this Technical Data

## Technical Data :

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CASE OUTLINE AND DIMENSIONS.  
Thyristor

R 2 0 0 C H 2 0 F J O - Power



OUTLINE DIMENSIONS - CASE 3T				
DIMENSIONS	Min. mm	Max. mm	Min. In.	Max. In.
DIAM A	33.02	34.29	1.30	1.35
DIAM B	55.88	63.50	2.20	2.50
DIAM C	--	54.61	--	2.15
D	0.76	--	0.03	--
E	25.40	27.18	1.00	1.07
F	3.30	3.81	0.13	0.15
G	1.78	2.03	0.07	0.08
H	--	36.32	--	1.43

OUTLINE CONFORMS TO JEDEC TO-200AC